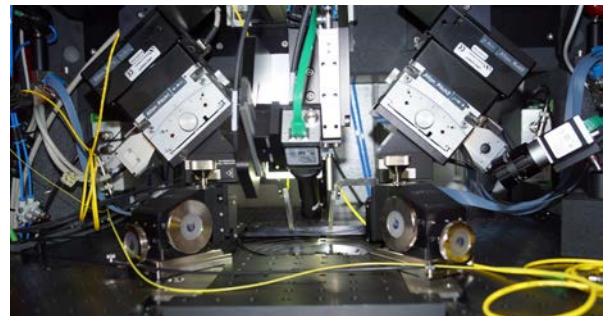


## NanoTest SiP Characterization for Si Photonics Devices

Especially designed for the requirements of Silicon Photonics devices, the NanoTest SiP performs the optical and electrical characterization of structures on wafers with up to 12" (300 mm) diameter. Electrical probes are manually positioned and the wafer is shuttled underneath the probes from device to device and thus contacted electrically. The optional wafer chuck provides temperature control between 20° C and 100° C.

Two 6-axes alignment stacks position the optical single or multi-channel probes with active alignment and 100 nm repeatability. Machine vision cameras both in the visible and as an option in the near infrared range are used for the pre-alignment. The subsequent active alignment to a feedback signal guarantees optimal coupling efficiency.

- **Suitable for 8" or 12" wafers**
- **20 nm resolution/100 nm repeatability for optical probing**
- **Heated Chuck Option**
- **Optional Packaging Capability**



*Standard Configuration for Volume Testing*

With the optional OptoSpin fast alignment engine, the alignment time per device will be cut to less than a second.

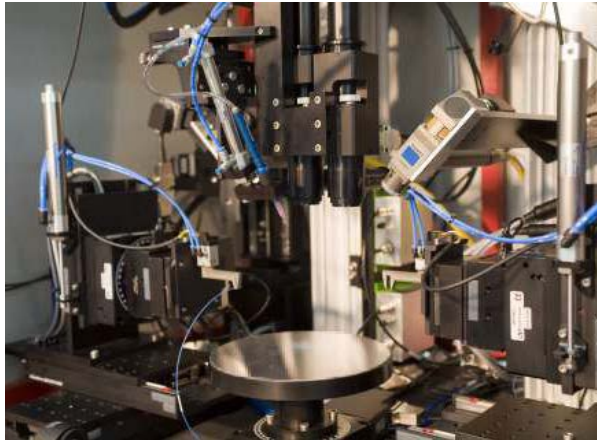
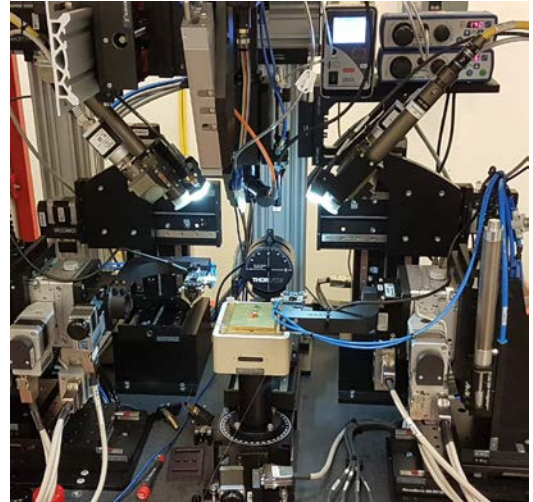
The central chuck is replaced with a versatile mounting interface for packaging capability. Resin dispensation and UV curing, laser welding and/or laser soldering capability will be added. The alignment stacks precisely position optical components such as fibers, fiber arrays, lenses, lens arrays, detectors and lasers.

For packaging requirements, nanosystec offers customized configurations taking the specific device requirements into account.

# NanoGlue/NanoWeld Packaging for SiP Devices

Epoxy gluing with UV curing, laser soldering and/or laser welding are the standard assembly techniques for chip and fiber mounting. One or more of these assembly methods can be combined into a single station for device development.

The NanoGlue and NanoWeld packaging stations provide optical and electrical characterization capabilities with manual electrical probing for small volumes.



## TestMaster Software

The versatile software package TestMaster allows for complete process automation. With a different user interface, the various functions and devices can be controlled directly. Interfaces allow for the communication with other programs such as Python or Matlab and also with databases.



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